CALL FOR PAPERS
RECENT ADVANCES IN COMPUTER SCIENCE AND COMMUNICATIONS
SCOPUS Indexed

SPECIAL ISSUE
FOURTH INDUSTRIAL REVOLUTION BASED TECHNOLOGY AND PRACTICES

Impressive progress has been made in recent years, driven by exponential increases in computing power. The interfacing of Digital Technology in industrial operation has improved efficiency and quality of products & services. Advancements in Artificial Intelligence, Internet of Things (IoT), Virtual / Augmented Reality, Additive Manufacturing (3D Printing), Cyber-physical systems (CPS), cloud computing (CC) and Robotics has significantly influenced industrial efficiency and performance. A fourth industrial revolution in manufacturing i.e. Industry 4.0, brings a whole new perspective to the industry which can collaborate with new technologies to get maximum output with minimum resource utilization in Manufacturing. Fourth Industrial generation will use 'Digital Reality' to change business practice, consumer behavior, operation decision and product precision. It will change the environment of employment requiring different skills and levels of knowledge, and it will redistribute wealth toward innovation and technology from resource and capital possessions.

The purpose of this special issue is to provide an international forum for scientists, engineers, and researchers all over the world to present and to bring insights of digital transformation of the industry or what we call industry 4.0. The change is based on the adoption of new technologies for the progressive automation of the production process. It is about innovative technologies whose application to the industry will be developed day by day. We particularly encourage submitting high quality original, previously unpublished research work.

Potential topics include but are not limited to the following

- Industrial Internet of Things
- Augmented and Virtual Reality
- Big Data and Analytics
- Robotics and collaborative robots
- 3D Printing and additive manufacturing
- Data Communication, Computer Network and Security & Forensic
- Blockchain and Quantum Computing
- Cloud Computing and Ambient Intelligence
- 3G/4G/5G Network Evolutions
- Computational Intelligence and Evolutionary Computation
- Industry 4.0
- Nanotechnologies
- Sensor Networks
- Power Electronics
- Design Automation
- Machine to Machine
- Medical Diagnosis
- Cyber security
- Cognitive Computing
- Neuromorphic Systems
- Autonomous Robots
- Remote Sensing
- Design for Disassembly
- Energy and climate policy
- Distributed and parallel systems
- VLSI and Large-scale applications
- Beyond LTE-A, WiSN
- Biomedical Engineering
- Decision Support and Recommender Systems
- Technology innovation for a green economy
- Advanced Wireless Systems & Technologies
- Artificial Neural Networks and Artificial Intelligence
- Machine Learning and Computer Vision
- Expert Systems and Intelligent Agents
- Human Computer Interaction
- Geographic Information Systems
- Image Processing and Pattern Recognition
- Information Retrieval, Natural Language Processing, and Ontology
- Biometric advanced– manufacturing
- Sustainable waste management
- Sustainable and resource efficient building design
- Satellite Communications & Telecommunication Systems

First Call: Submission Deadline
Submission Deadline December 31, 2021
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All submissions must be original and may not be under review by another publication. All submitted papers will be reviewed on a double-blind, peer review basis. Papers must follow IEEE style for reference citations. Peer review of special/thematic issue papers will be carried out by Bentham Science Publishers.

PUBLICATION DATE
It will be notified through mail